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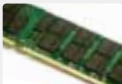# Read Statement

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ATP Industrial Grade DRAM Modules

Targeted Product Portfolio, Engineered Specifically for Your Mission Critical Applications

Product	Category	Speed (MT/s)	Form Factor	Features
DDR4	RDIMM RDIMM VLP UDIMM/UDIMM ECC SO-DIMM ECC	2133	• Low profile • Very Low Profile (VLP) options (VLP: 0.74" height)	• Density: 4GB to 16GB • Increase performance and bandwidth which is up to 3200 MT/s • Decrease voltage for better power consumption • Provide better reliability, availability and serviceability (RAS) and improve data integrity as well.
DDR3	LRDIMM RDIMM UDIMM/UDIMM ECC SO-RDIMM SO-DIMM/SO-DIMM ECC mini-RDIMM mini-UDIMM ECC	1866 1600 1333 1066	• Low profile • Very Low Profile (VLP) options (VLP: 0.74" height) • Ultra Low Profile (ULP) options (ULP: 0.7"~0.72" height)	• Density: 1GB to 32GB 32GB to 64GB(LRDIMM) • Chipkill support • Fly-by command/address/control bus with on-DIMM termination. • Higher bandwidth performance, effectively up to 1866 MT/s • Better performance at low power; 1.5V (Normal) and 1.35V(Low Voltage)
DDR2	RDIMM UDIMM/UDIMM ECC SO-RDIMM SO-CDIMM SO-DIMM mini-RDIMM FB-UDIMM*	800 667 533 400	• Low Profile • Very Low Profile (VLP) options (VLP:0.72"~0.74" height)	• Density: 1GB to 8GB • Chipkill support **FB-DIMM** • Low power and low voltage options • Apple FB-DIMM
DDR*	UDIMM/UDIMM ECC SO-CDIMM SO-DIMM	400 333 266	• Low Profile • Very Low Profile (VLP) options (VLP:0.72"~0.74" height)	• Density: 512MB to 1GB • Chipkill support
SDRAM*	RDIMM UDIMM/UDIMM ECC SO-UDIMM	PC 133 PC 100	• Low Profile • Very Low Profile (VLP) options (VLP:0.72"~0.74" height)	• Density: 256MB to 1GB • Chipkill support • Legacy system support

Product Portfolio	Category	Product	Features
Industrial Grade Family	SO-DIMM UDIMM RDIMM	DDR3 DDR2 DDR* SDRAM*	• Extended temperature: -40°C ~ +85°C • Controlled BOM and SPD • For mission critical industrial applications • conformal coating

*   Available on a project basis.

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